

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of

HONG et al.

Atty. Ref.: 2826-9

Serial No. unknown

Group:

Filed: January 17, 2002

Examiner:

For: METHOD AND APPARATUS FOR CUTTING A MULTI-LAYER SUBSTRATE  
BY DUAL LASER IRRADIATION

\* \* \* \* \*

January 17, 2002

Assistant Commissioner for Patents  
Washington, DC 20231

Sir:

**PRELIMINARY AMENDMENT**

In order to place the above-identified application in better condition for  
examination, please amend the application as follows:

**IN THE CLAIMS**

Please substitute the following amended claims for corresponding claims  
previously presented. A copy of the amended claims showing current revisions is  
attached.